



SOT2053-1

HLSON10, thermal enhanced low profile small outline package, no leads, 10 terminals, 1.7 mm pitch, 7 mm x 10 mm x 1.51 mm body

9 March 2020

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HLSON10
Package style descriptive code	HLSON (thermal enhanced low profile small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-11-2019
Manufacturer package code	98ASA01557D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	9.9	10	10.1	mm
package width	6.9	7	7.1	mm
package height	1.46	1.51	1.56	mm
nominal pitch	-	1.7	-	mm
actual quantity of termination	-	10	-	



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2 Package outline

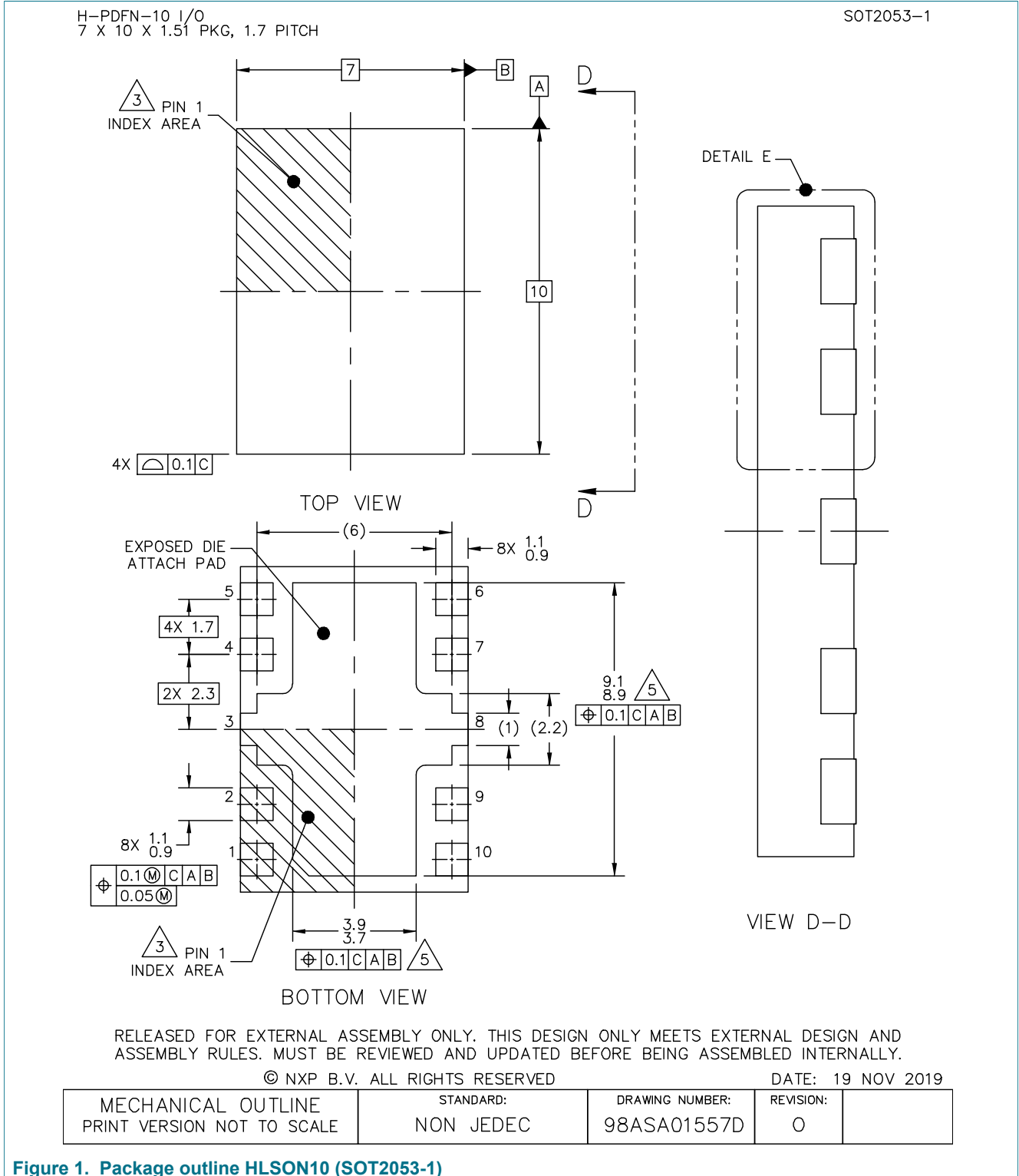
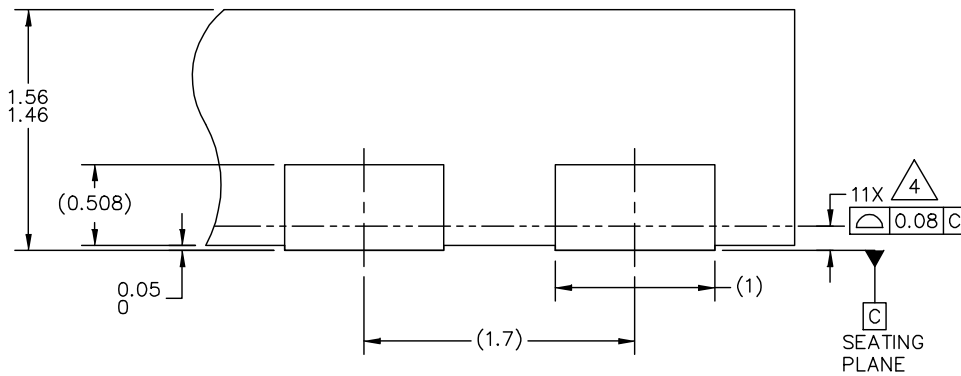


Figure 1. Package outline HLSON10 (SOT2053-1)

HLSON10, thermal enhanced low profile small outline package, no leads, 10 terminals, 1.7 mm pitch, 7 mm x 10 mm x 1.51 mm body

H-PDFN-10 I/O
7 X 10 X 1.51 PKG, 1.7 PITCH

SOT2053-1



DETAIL E
VIEW ROTATED 90°CW

RELEASED FOR EXTERNAL ASSEMBLY ONLY. THIS DESIGN ONLY MEETS EXTERNAL DESIGN AND ASSEMBLY RULES. MUST BE REVIEWED AND UPDATED BEFORE BEING ASSEMBLED INTERNALLY.

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DATE: 19 NOV 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01557D	REVISION: 0	
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Figure 2. Package outline detail HLSON10 (SOT2053-1)

HLSON10, thermal enhanced low profile small outline package, no leads, 10 terminals, 1.7 mm pitch, 7 mm x 10 mm x 1.51 mm body

3 Soldering

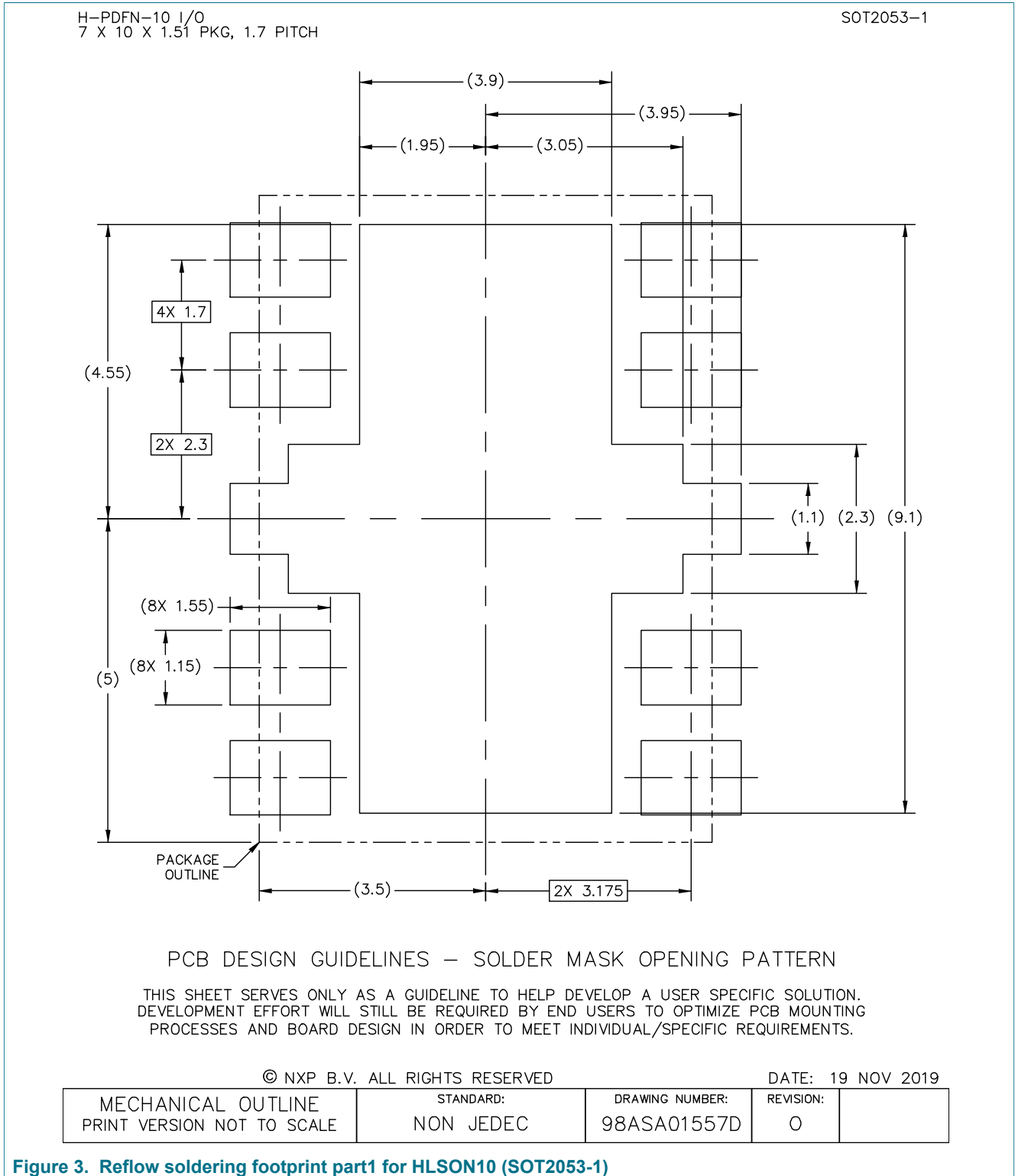
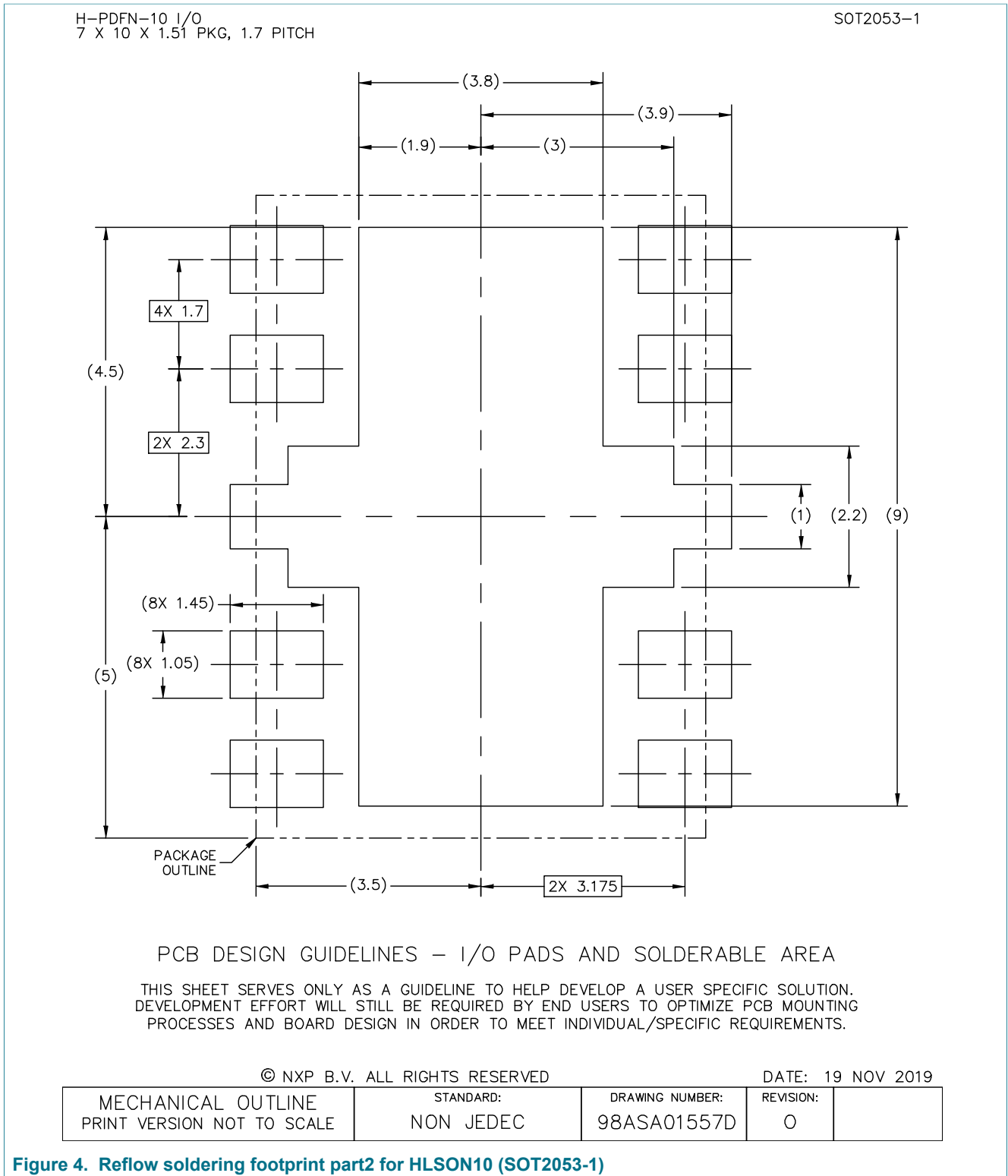


Figure 3. Reflow soldering footprint part1 for HLSON10 (SOT2053-1)

HLSON10, thermal enhanced low profile small outline package, no leads, 10 terminals, 1.7 mm pitch, 7 mm x 10 mm x 1.51 mm body



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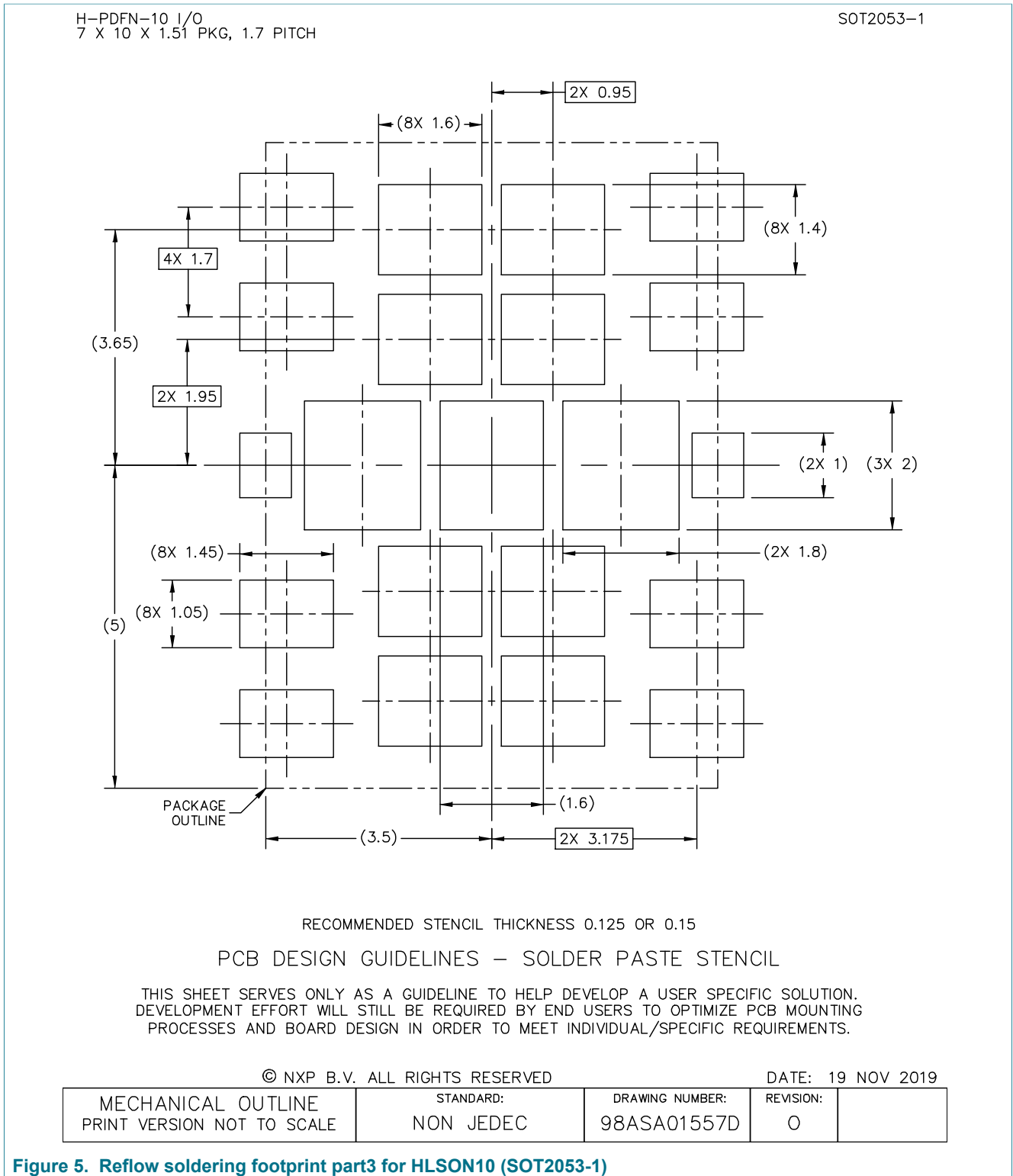


Figure 5. Reflow soldering footprint part3 for HLSON10 (SOT2053-1)

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H-PDFN-10 I/O
7 X 10 X 1.51 PKG, 1.7 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. RADIUS ON DIE ATTACH FLAG IS OPTIONAL.

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Figure 6. Package outline note HLSON10 (SOT2053-1)

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4 Legal information

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